

## N-Channel Enhancement Mode Field Effect Transistor With Fast Body Diode

### FEATURES

Type	$V_{DSS}$ @ $T_J$ max	$R_{DS(ON)}$	$I_D$	@ $V_{GS}$
CEW43N60SF	650V	68mΩ	43A	10V

■ Super high dense cell design for extremely low  $R_{DS(ON)}$ .

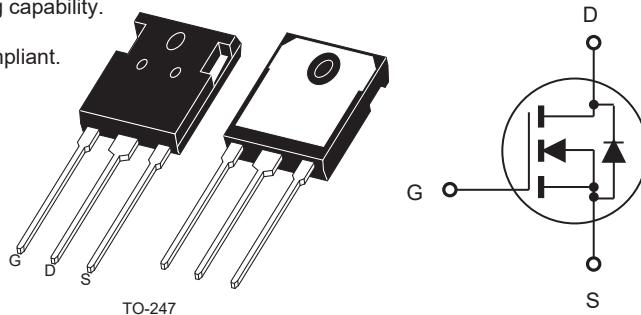
■ High power and current handing capability.

■ Pb-free lead plating ; RoHS compliant.

■ Halogen Free.

■ Fast reverse recovery time.

■ TO-247 package.



### ABSOLUTE MAXIMUM RATINGS $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	600	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current-Continuous @ $T_C = 25^\circ\text{C}$ @ $T_C = 100^\circ\text{C}$	$I_D$	43 27	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	172	A
Maximum Power Dissipation @ $T_C = 25^\circ\text{C}$ - Derate above $25^\circ\text{C}$	$P_D$	297 2.37	W W/ $^\circ\text{C}$
Single Pulsed Avalanche Energy <sup>d</sup>	$E_{AS}$	200	mJ
Single Pulsed Avalanche Current <sup>d</sup>	$I_{AS}$	20	A
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.42	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$



# CEW43N60SF

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	600			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0\text{V}$			10	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	3		5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 21\text{A}$		57	68	$\text{m}\Omega$
Gate Input Resistance	$R_g$	f=1MHz,open Drain		1.9		$\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		3500		pF
Output Capacitance	$C_{\text{oss}}$			130		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			5		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 400\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 25\Omega$		81		ns
Turn-On Rise Time	$t_r$			102		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			179		ns
Turn-Off Fall Time	$t_f$			64		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 480\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$		74		nC
Gate-Source Charge	$Q_{\text{gs}}$			18		nC
Gate-Drain Charge	$Q_{\text{gd}}$			35		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_S$				43	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_S = 21\text{A}$			1.4	V
Reverse Recovery Time	$T_{\text{rr}}$	$I_F = 27\text{A}, di/dt = 100\text{A}/\mu\text{s}$		180		ns
Reverse Recovery Charge	$Q_{\text{rr}}$			1.3		$\mu\text{C}$

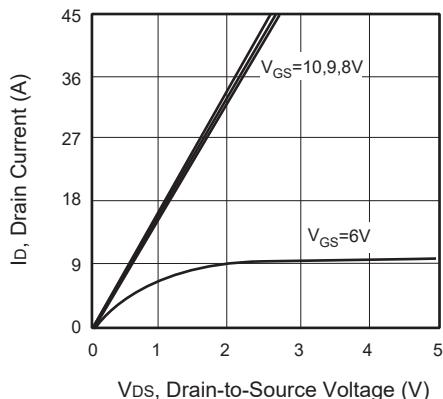
Notes :

a.Repetitive Rating : Pulse width limited by maximum junction temperature.

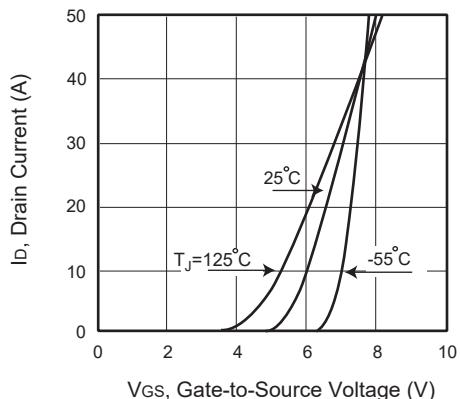
b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

c.Guaranteed by design, not subject to production testing.

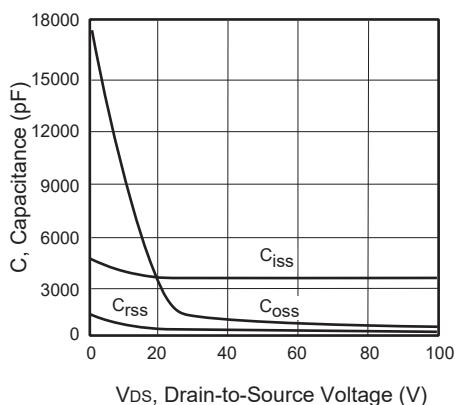
d.L = 1mH,  $I_{AS} = 20\text{A}$ ,  $V_{DD} = 50\text{V}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .



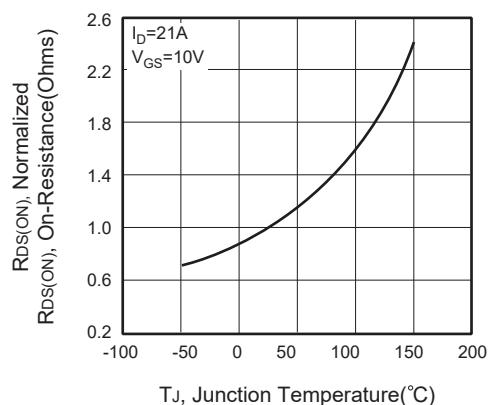
**Figure 1. Output Characteristics**



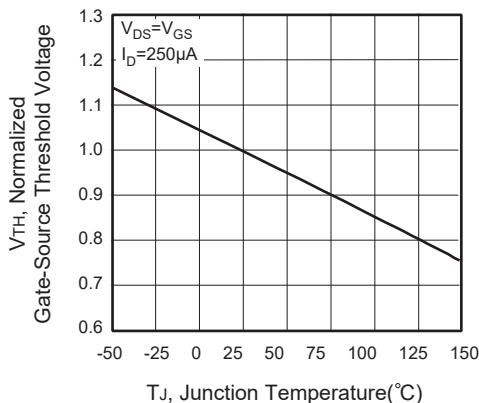
**Figure 2. Transfer Characteristics**



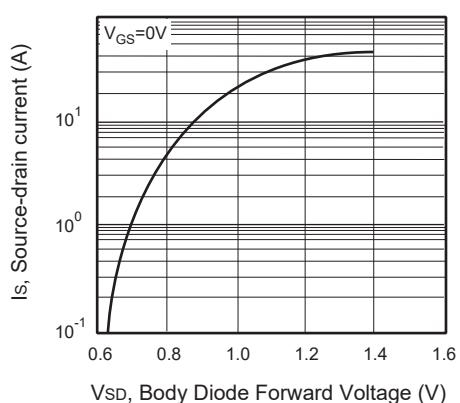
**Figure 3. Capacitance**



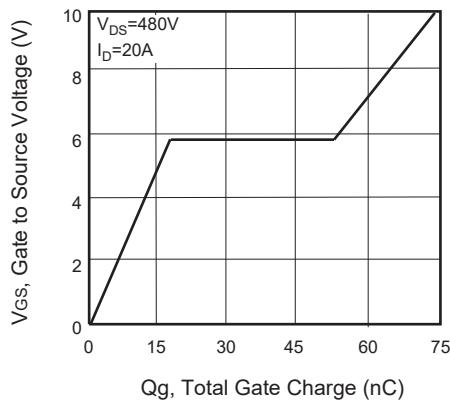
**Figure 4. On-Resistance Variation with Temperature**



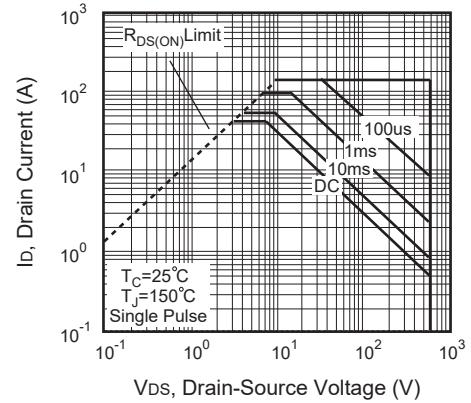
**Figure 5. Gate Threshold Variation with Temperature**



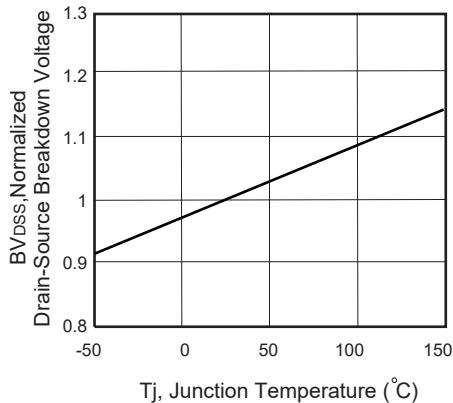
**Figure 6. Body Diode Forward Voltage Variation with Source Current**



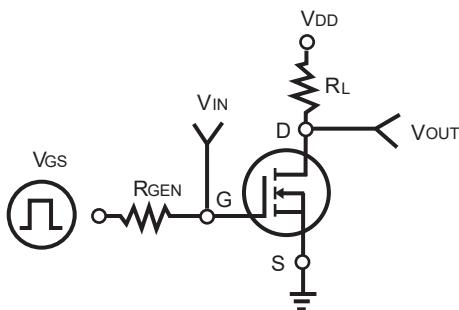
**Figure 7. Gate Charge**



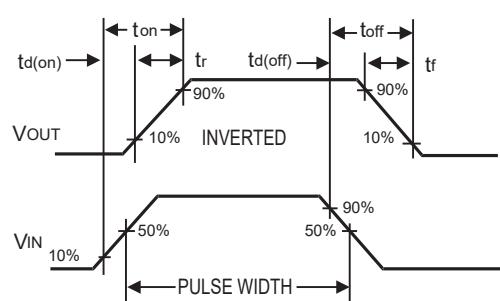
**Figure 8. Maximum Safe Operating Area**



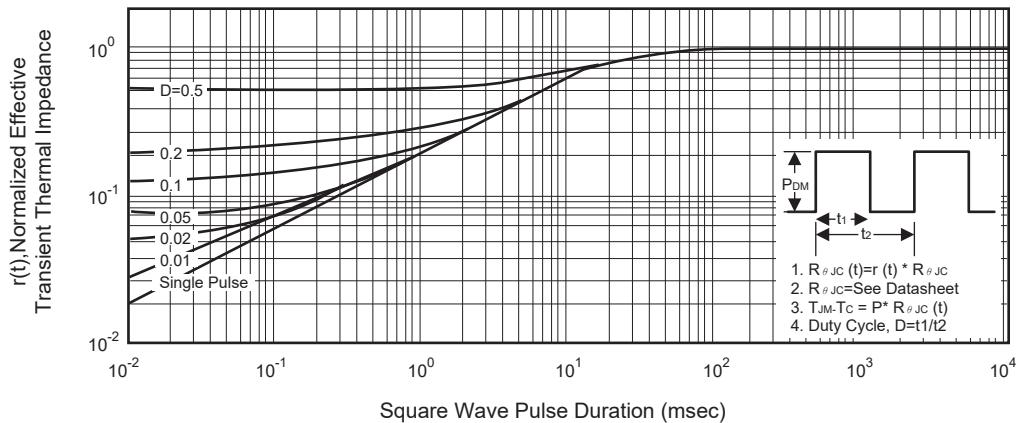
**Figure 9. Breakdown Voltage Variation VS Temperature**



**Figure 10. Switching Test Circuit**

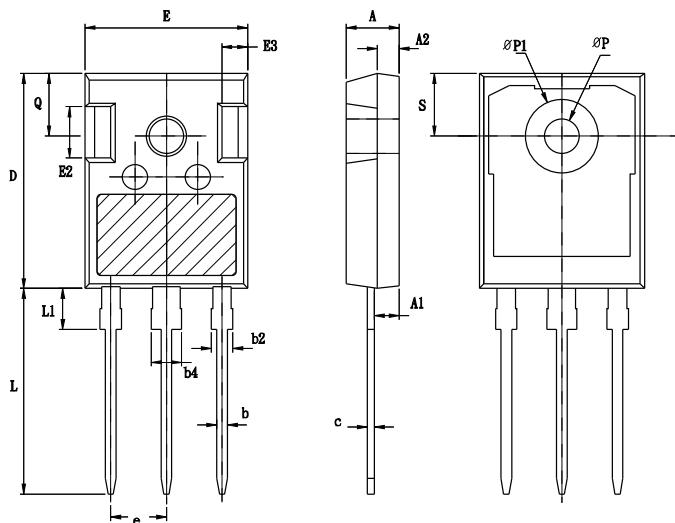


**Figure 11. Switching Waveforms**



**Figure 12. Normalized Thermal Transient Impedance Curve**

TO-247 產品外觀尺寸圖 (Product Outline Dimension)



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.830	5.210	0.190	0.205
A1	2.310	2.510	0.091	0.099
A2	1.900	2.160	0.075	0.085
b	1.140	1.400	0.045	0.055
b2	1.910	2.200	0.075	0.087
b4	2.960	3.160	0.117	0.124
C	0.550	0.750	0.022	0.030
D	20.800	21.340	0.819	0.840
e	5.45BSC		0.215BSC	
E	15.700	16.130	0.618	0.635
E2	4.320	5.100	0.170	0.201
E3	1.58	2.60	0.062	0.102
L	19.80	20.57	0.780	0.810
L1	3.81	4.32	0.150	0.170
ΦP	3.5	3.7	0.138	0.146
ΦP1	~	7.3	~	0.287
S	6.15BSC		0.242BSC	
Q	5.59	6.2	0.220	0.244